

SUPPLEMENTAL APPLICATION DATA SHEET

The information shown below supercedes and replaces that originally given on the Application Data Sheet filed with this application on July 23, 2001.

Inventor Information

Inventor One Given Name:: Ye
Family Name:: Bangce
Name Suffix::
Postal Address Line One:: #130 Mei Long Road
Postal Address Line Two::
City:: Shanghai
State or Province::
Country:: China
Postal or Zip Code:: 200237
City of Residence:: Shanghai
State or Prov. of Residence::
Country of Residence:: China
Citizenship Country:: China

Correspondence Information:

Correspondence Customer Number:: 23579
Telephone:: 404-817-8473
Fax:: 404-817-8588
Electronic Mail One:: jcstines@hklaw.com
Electronic Mail Two:: ppabst@hklaw.com

Application Information:

Title Line One:: MEDIUM AND LOW DENSITY GENE CHIPS
Title Line Two::
Title Line Three::
Total Drawing Sheets:: 2
Formal Drawings?: No
Application Type:: Utility
Docket Number:: JNB 100
Licensed US Govt. Agency::
Contract or Grant Numbers One::
Contract or Grant Numbers Two::
Secrecy Order in Parent Appl.?: No

Assignee:: Jiangnan Biotech Ltd.
State of Incorporation:: China

U.S.S.N. 09/912,673
Filed: July 23, 2001
Supplemental Application Data Sheet

Representative Information

Representative Customer Number:: 23579

Prior Foreign Applications

Foreign Application One:: 001044958
Filing Date:: July 23, 2000
Country:: China
Priority Claimed:: Yes

ATL1 #571450 v1